

Fig. 1

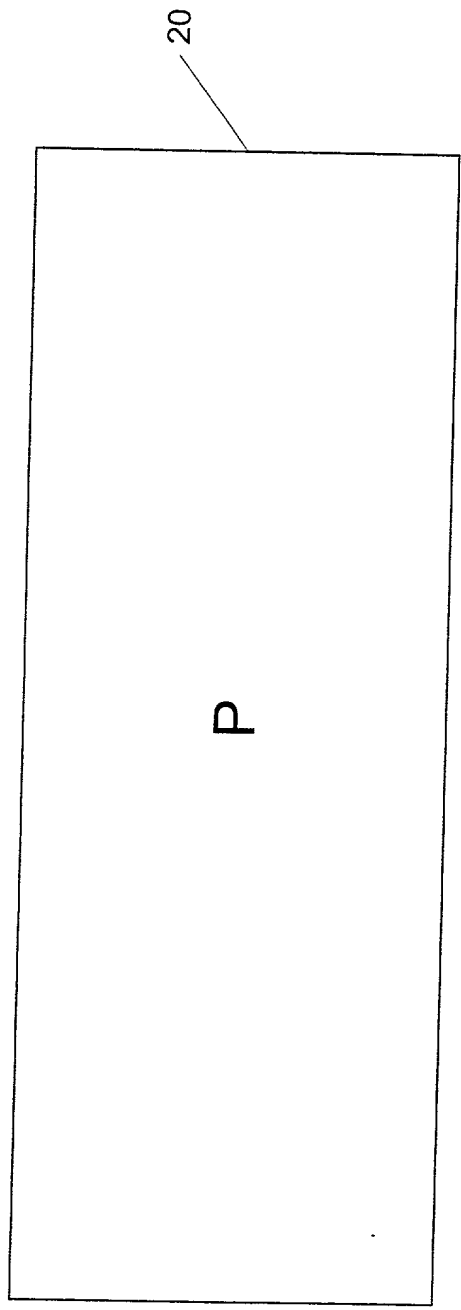


Fig. 2a

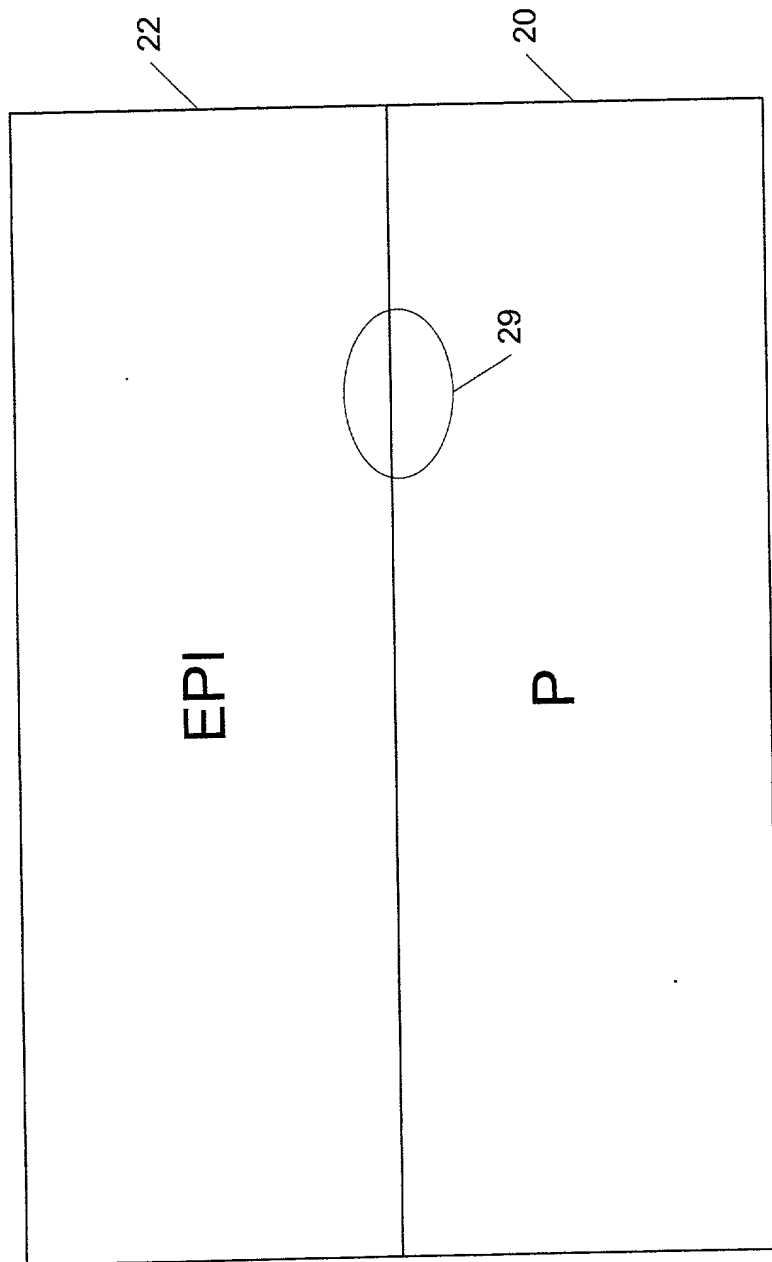


Fig. 2b

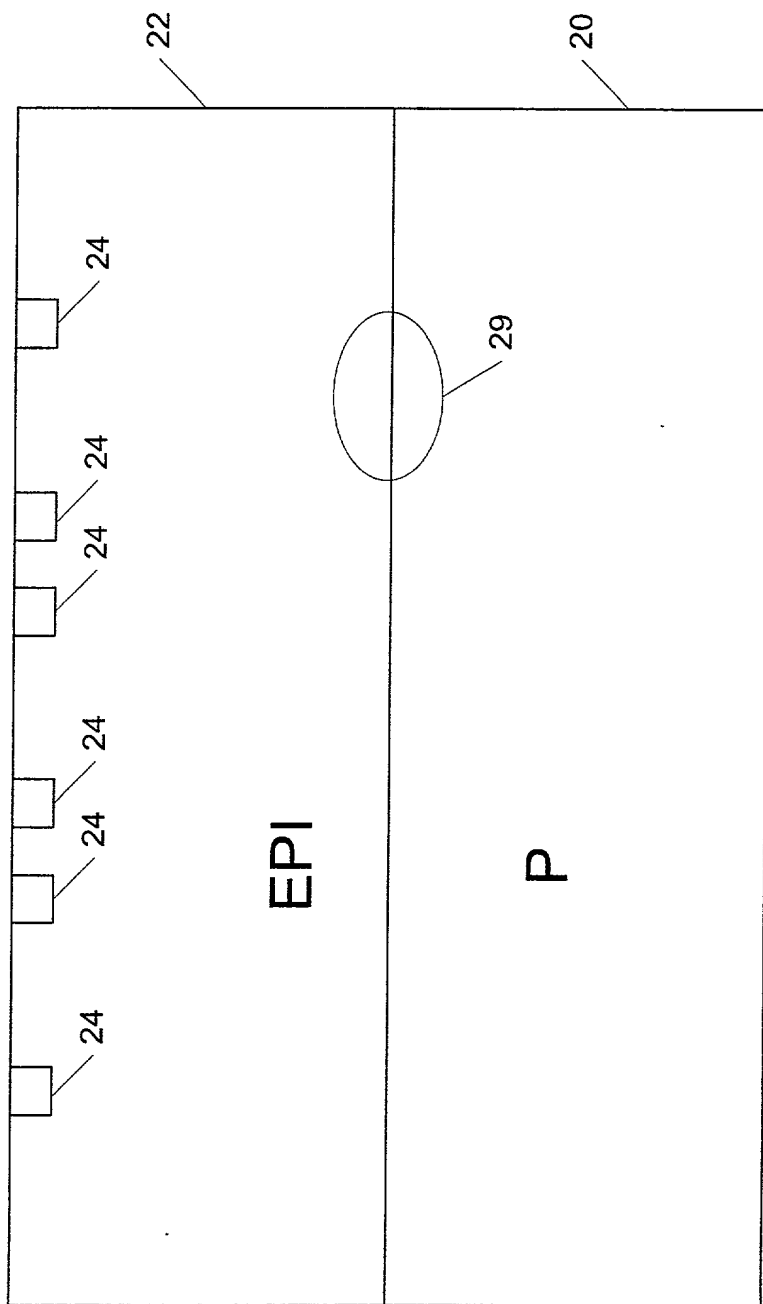


Fig. 2c

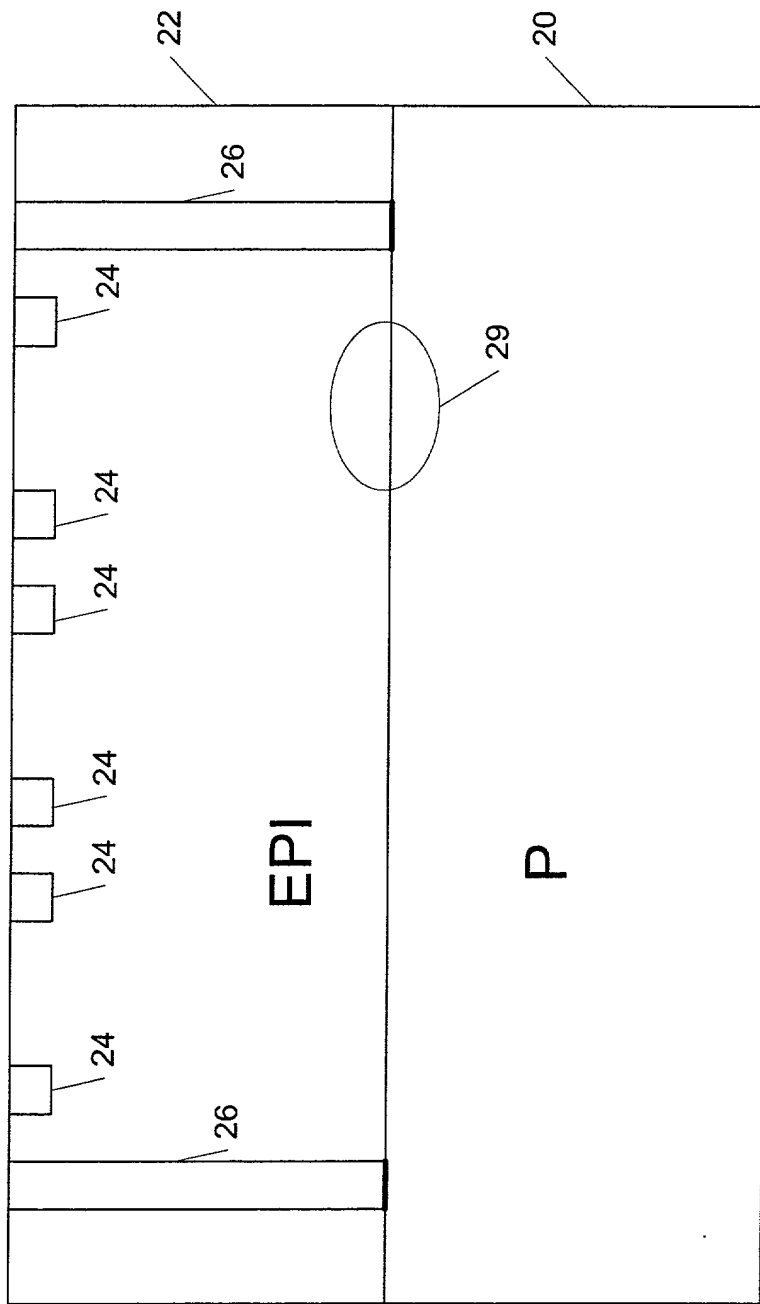


Fig. 2d

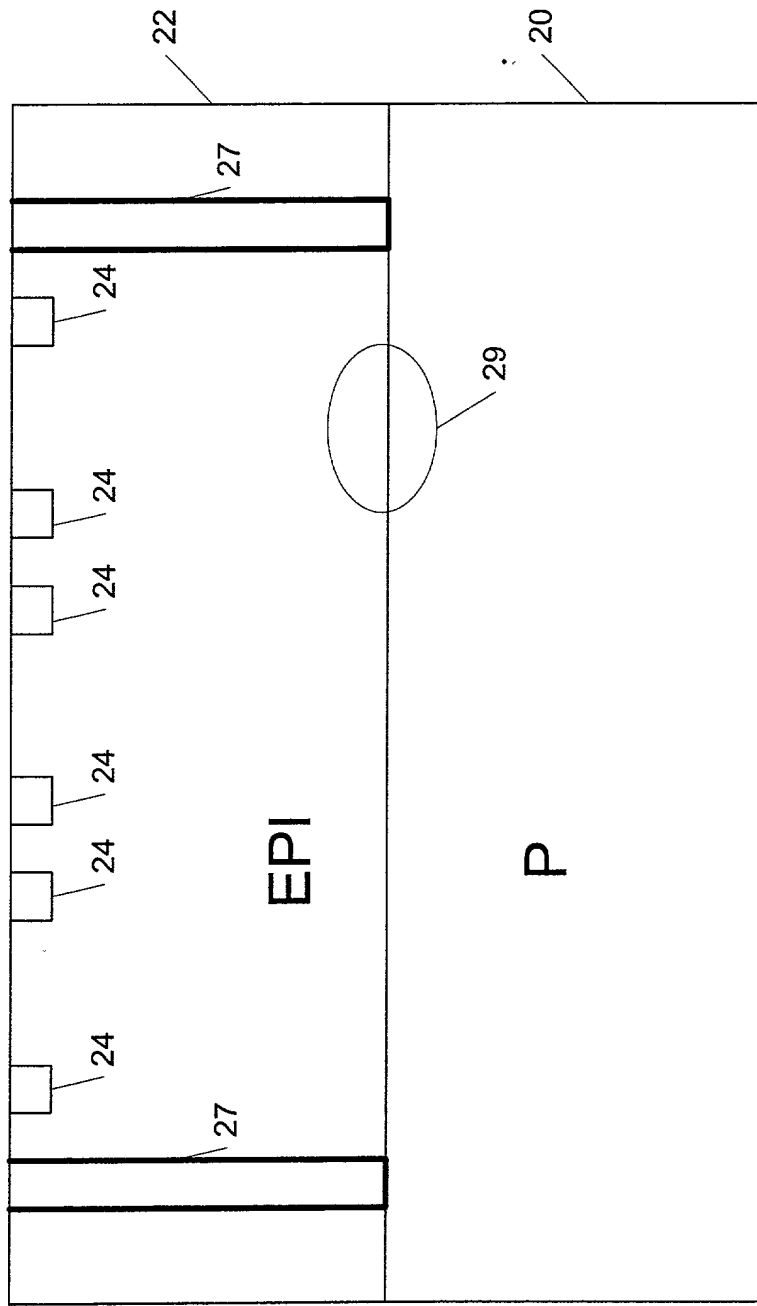


Fig. 2e

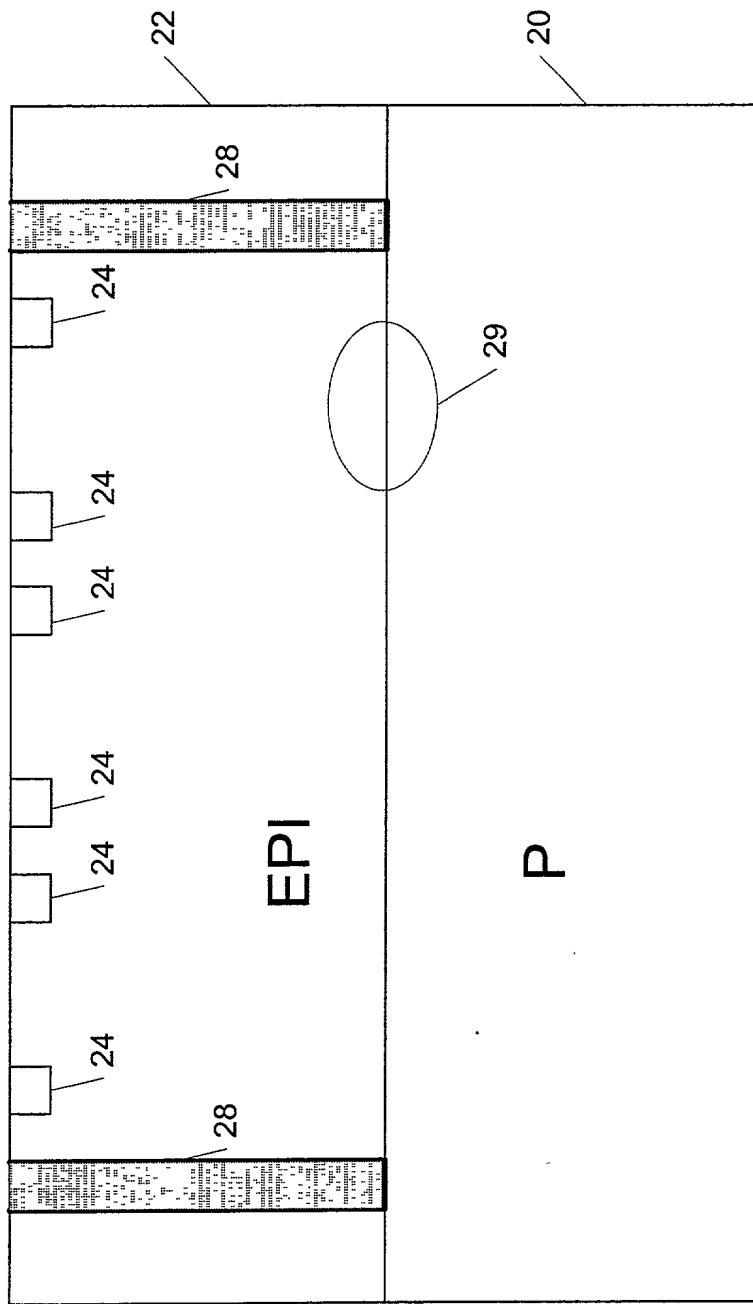


Fig. 2f

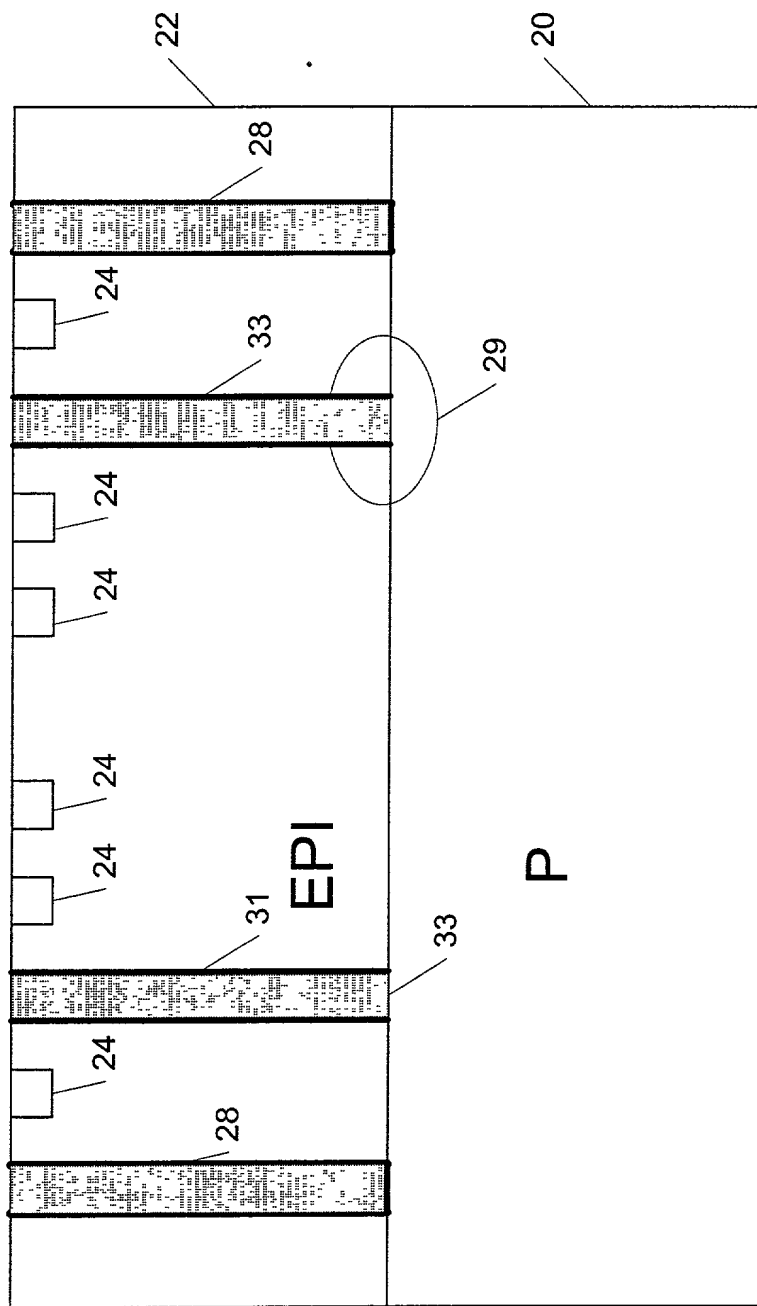


Fig. 29

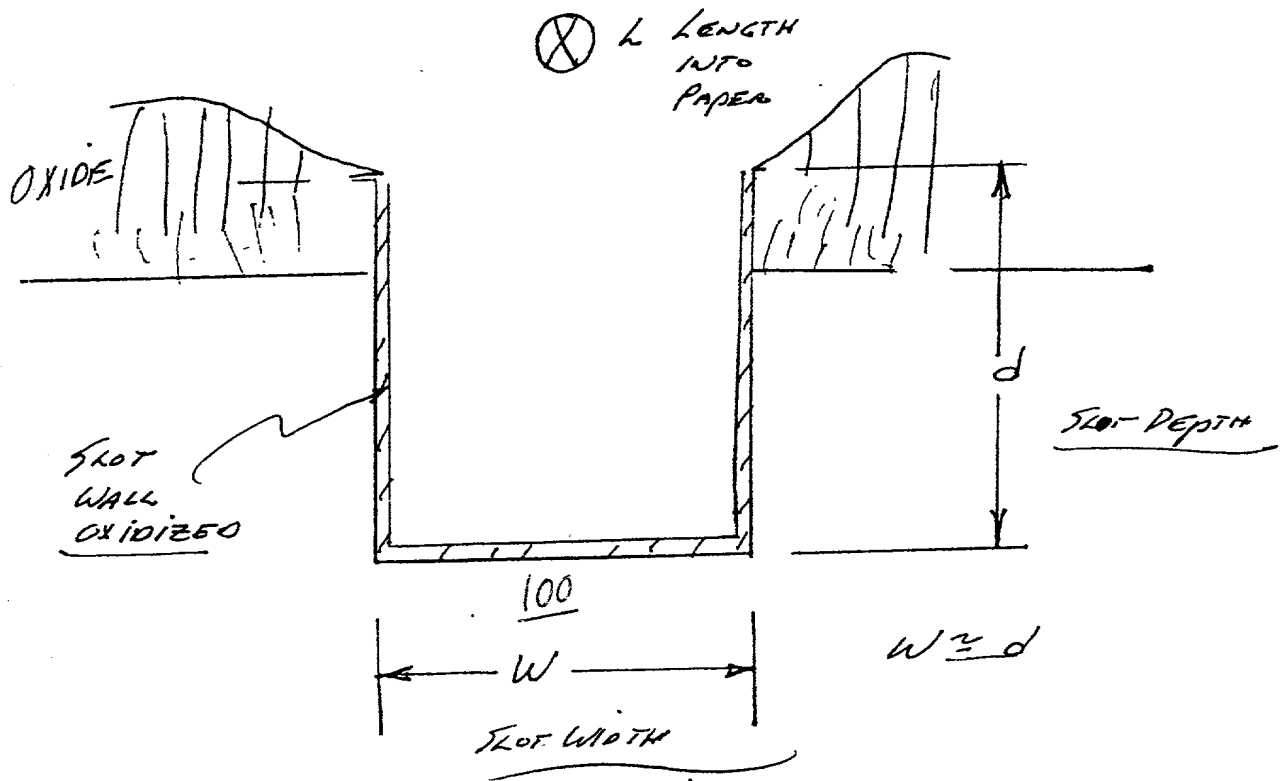


Fig. 3

1003429-12801

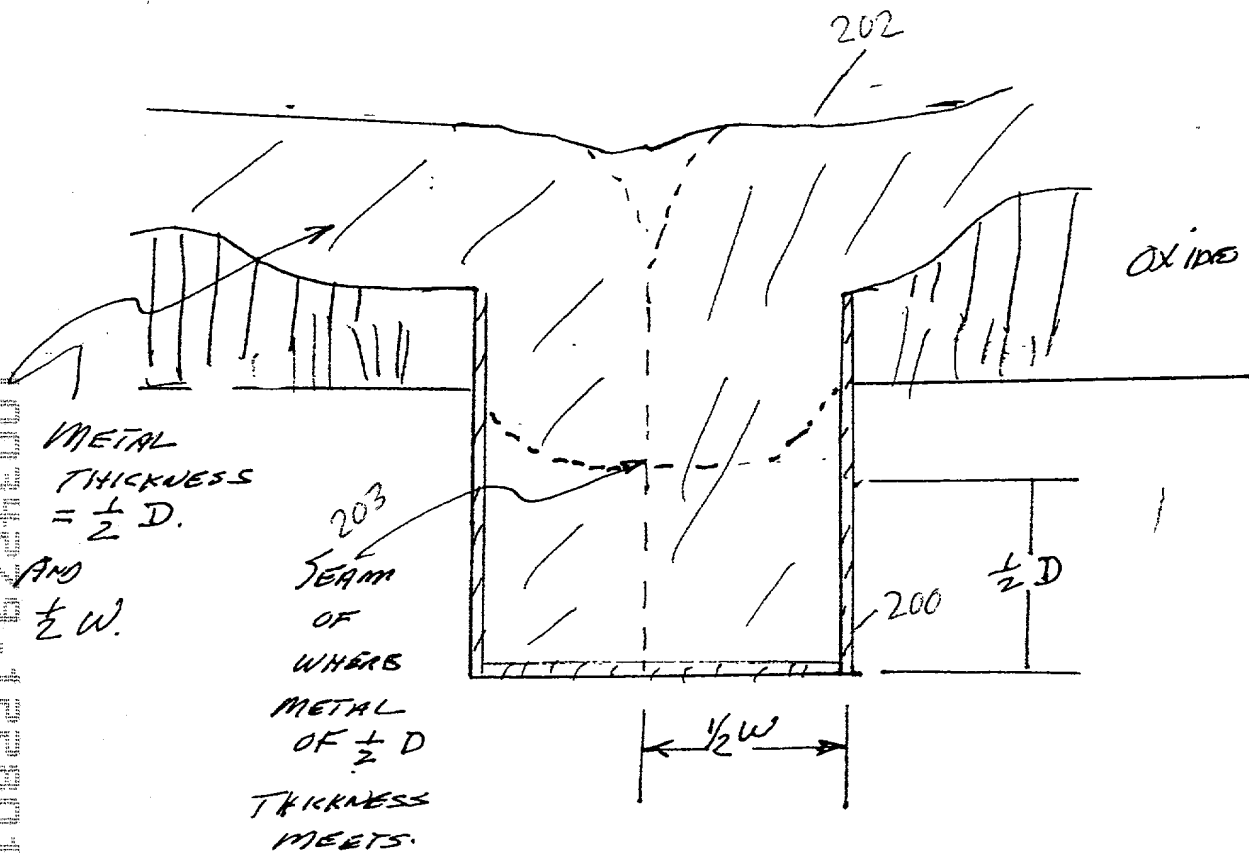
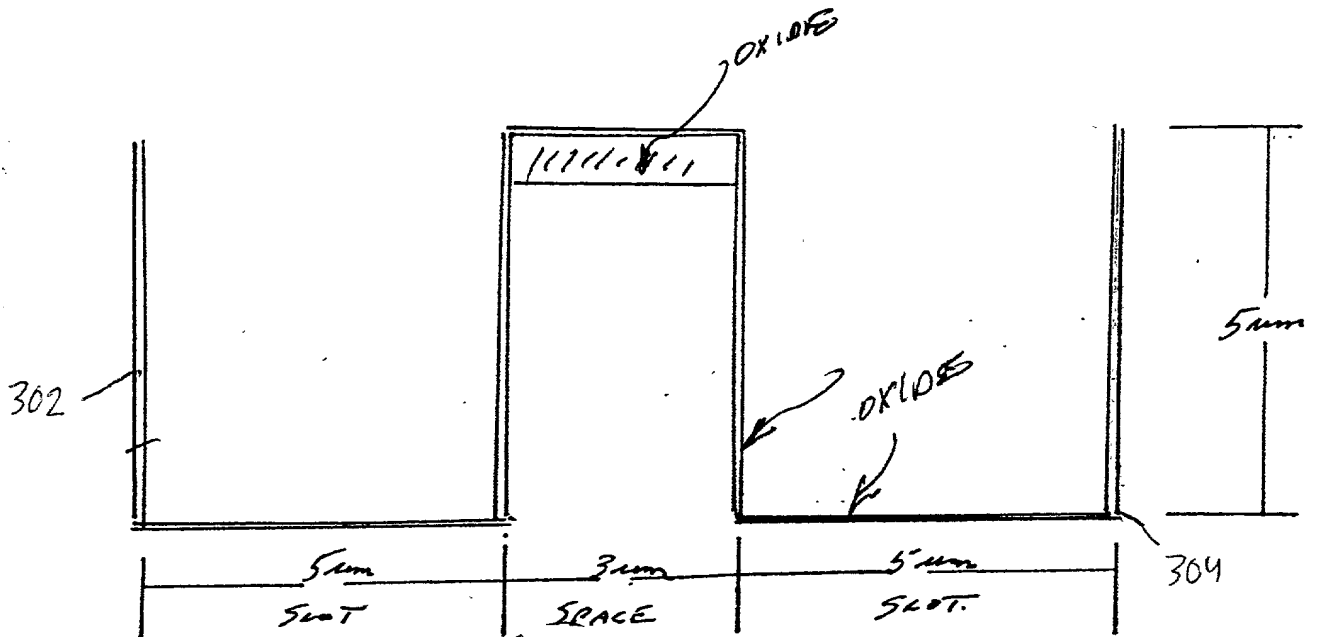
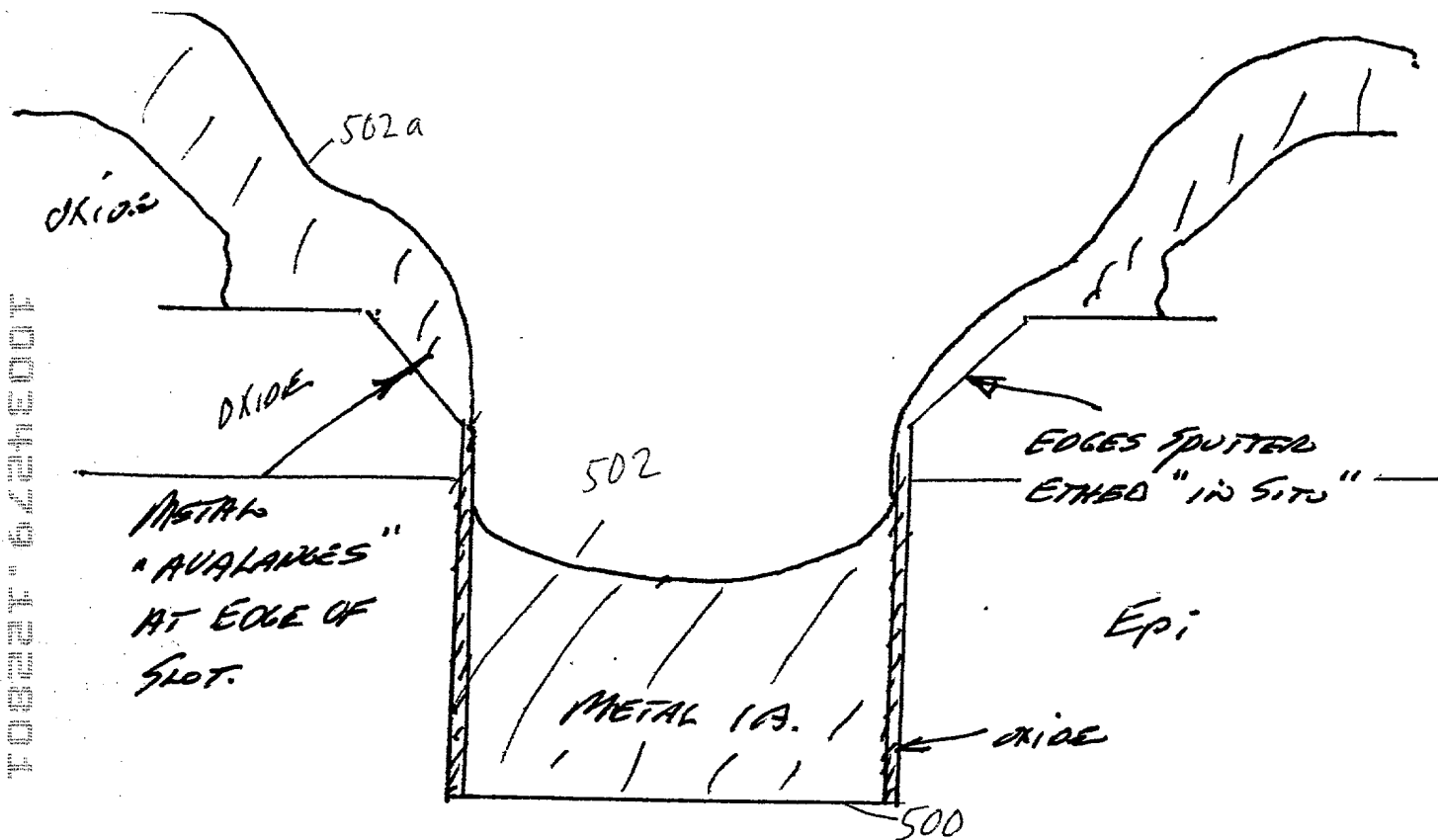


Fig. 4



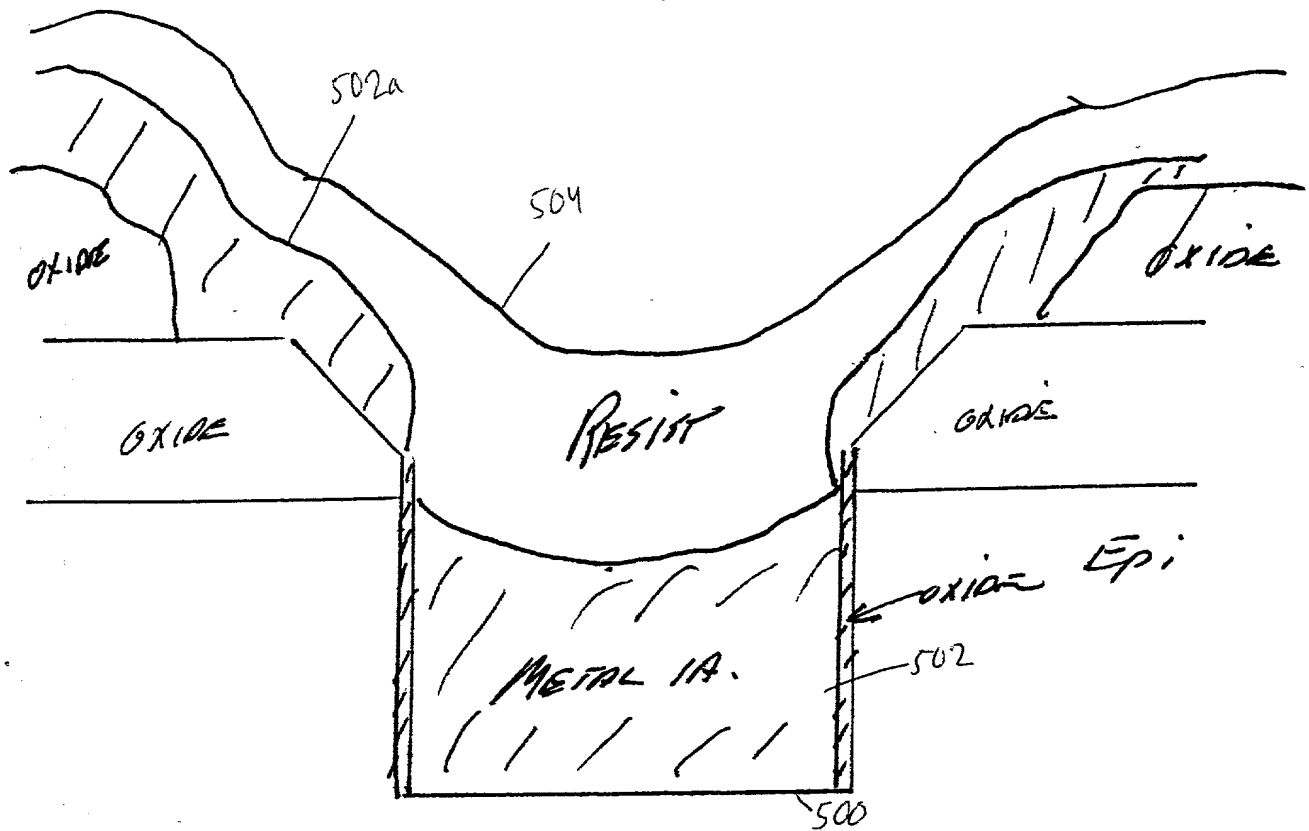
DOUBLE SLOT FOR
DOUBLE WIDTH OF METAL.
3mm SPACE BETWEEN SLOTS

Fig. 4a



Prior TO METAL 1A BEING
 SPUTTERED, THE EDGES OF THE OXIDES
 ARE SPUTTERED ETCHED "IN SITU" &
 1A DEPOSITED

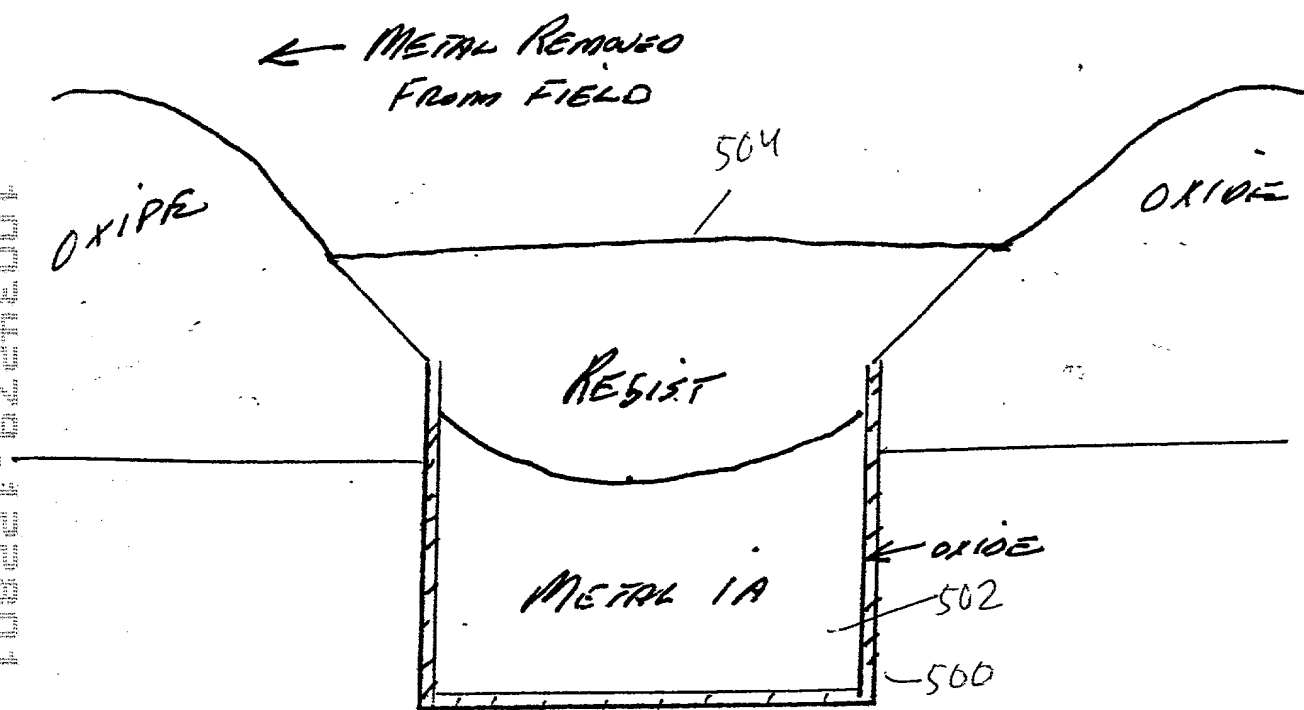
Fig. 5



RESIST COATING - THICK IN THE
SLOTS

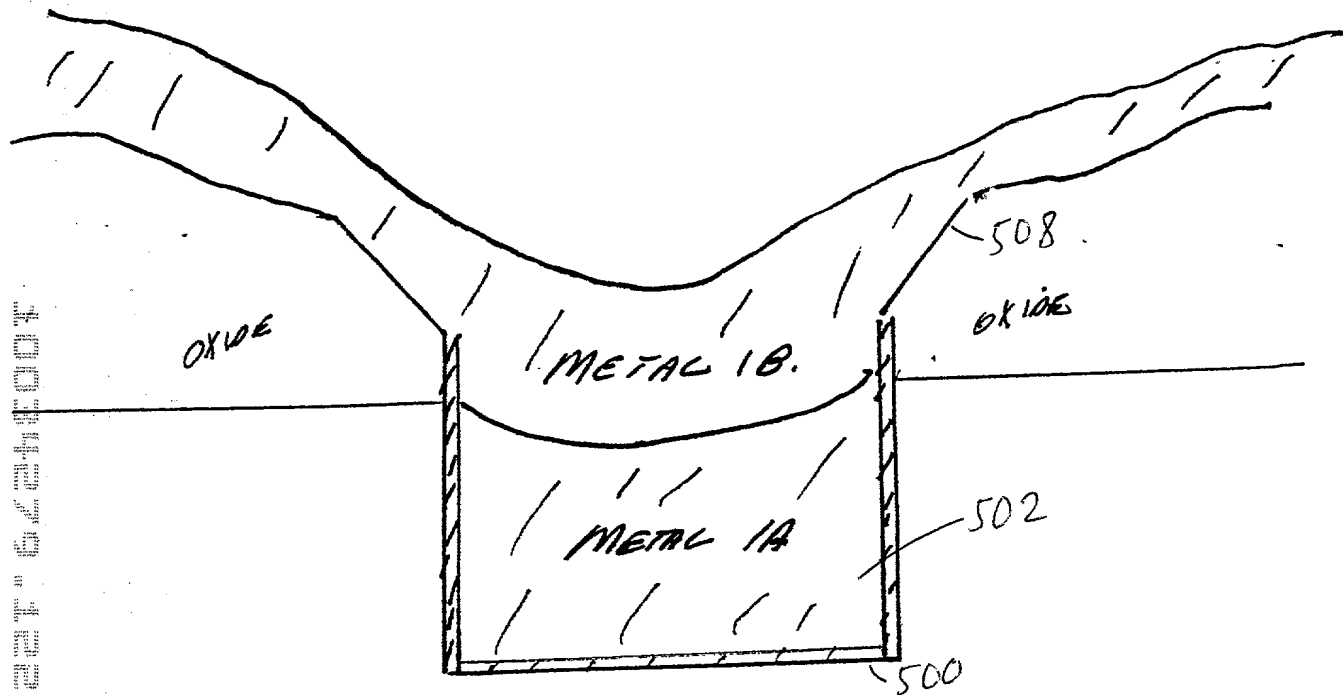
Fig. 6

10034279 122801



RESIST PATTERN ETCHED.
LEAVING RESIST IN TRENCHES
FIELD METAL ETCHED OFF.

Fig-7



RESIST STRIPPED & SECOND
METAL 1B SPUTTER DEPOSITED

Fig. 8

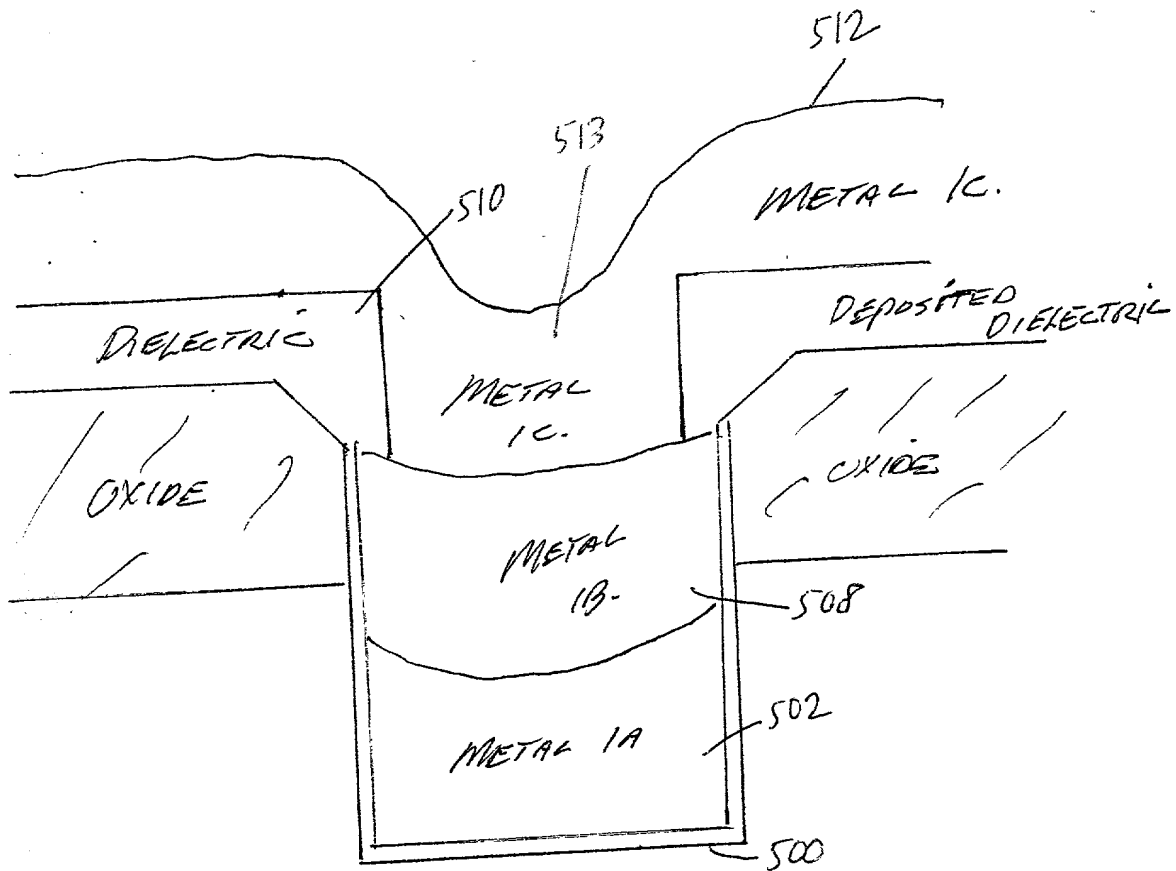


Fig. 9

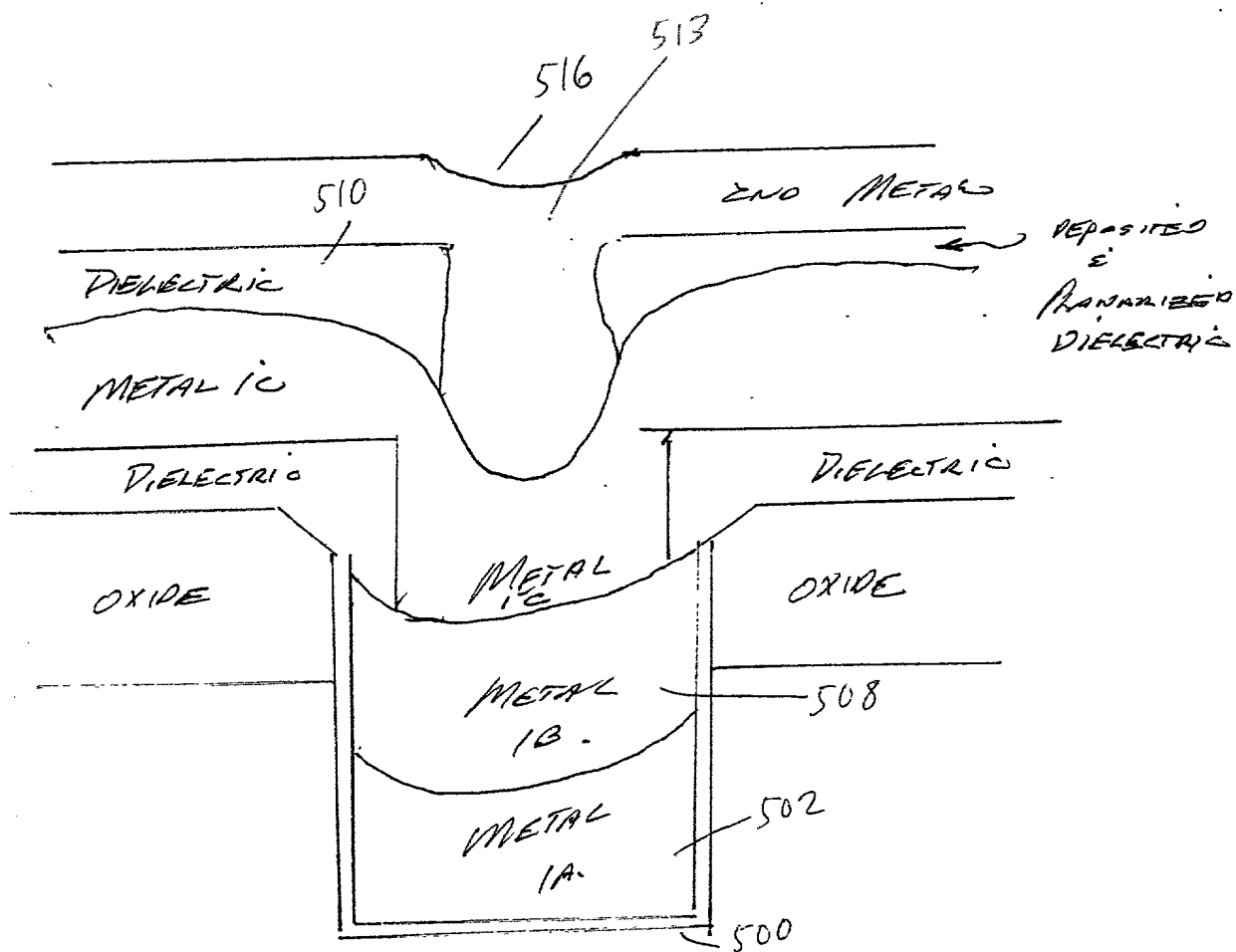
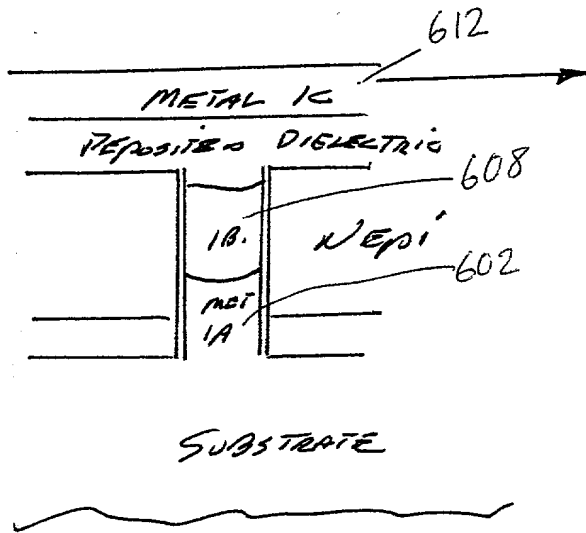


Fig. 10



METAL 1C
CONNECTS AN ISOLATED
ISLAND TO ADJACENT
ISOLATED EPI ISLANDS
AND CROSSES OVER THE
ISOLATION GROUND
STRAP BY NOT OPENING
A VIA IN THIS PORTION
TO ALLOW 1C TO BE
ISOLATED FROM GROUND.

Fig. 12